

AI IoT Advanced Control Edge Computing

ECS-SRIA workshop 18/05/2021 Marco Ceccarelli DG CONNECT European Commission

EC ambition



"In the global race for technological power, Europe will lead if we seize the opportunities of data, microelectronics and connectivity...

Without an **autonomous European capacity on microelectronics**, there will be no European **digital sovereignty**."

"By 2025, 80% of data will be generated and processed at the Edge...

The vast majority of data will not be created by us humans, but by objects and machines – the *Internet of Things*.

...this is a **huge potential source of growth** for Europe, which has the largest industrial market in the world, with leading players, particularly in the 4.0 industry'

Thierry Breton – EC Commissioner for Internal Market



AI, IoT, edge – trends and opportunities



- EU strengths in embedded, low-power, real-time => Edge computing is top strategic priority
- <u>Domain-specific architectures</u> for best performance/power Multifunctional integration (connectivity, sensing) - Invest in modular designs (<u>chiplets</u>), 3D/ <u>heterogeneous integration</u>
- IoT exponential growth, with 5G/6G / heterogeneous networks, getting smarter (AIoT)
- Proliferation of **AI**:
 - Fastest growing HW segment (40-80% CAGR), capturing 50% of system value; ML+ inference
 - EU has competences but lagging behind, must act fast to capture window of opportunity
- HW/SW co-design domain-specific software and algorithms
- <u>Architecture</u>: ARM solid for RT/HPC, RISC-V gaining ground from IoT, offering flexibility
- <u>New computation models</u> in-memory, analog, neuromorphic, photonics, quantum

Digital Design & IP

- EU must reduce vulnerabilities in **digital** domain, by developing **IP** and design capabilities:
 - **Grow competences** where EU is strong (automotive, industrial) with <u>leadership</u> ambitions (e.g. autonomous driving chips)
 - Address opportunities where EU has strong potential and critical gaps communications, edge computing/ AI, data infrastructure; ultra-low power, accelerators, photonics...
 - Establish a common EU IP platform for open-source ecosystem (<u>RISC-V</u> cores, extensions, transversal elements, verification tools, interfaces, libraries, EDA)

Vertical	Entry-level	Mid-range	High-end / Al
Automotive	Embedded controllers, ultra-low power	Real-time / safety-critical: Vision, motion control, engine management, safety, infotainment	ADAS/autonomous driving processors, sensor fusion
Industrial automation	Embedded controllers: ultra-low power, smart sensing	Embedded processors, sensor fusion; edge-cloud management	High-performance processors with AI acceleration, edge server processors
Communication	Baseband connectivity for wireless communication 5G/6G	Edge server processors, 5G/6G private networks, RF mgmt	5G/6G Base station front-end processors, V-RAN
Data infrastructure		Edge AI node processor	Processors for edge/fog servers; CPUs and accelerators (servers, HPC)
Other (Healthcare, CE, Defence, Aerospace…)	Embedded controllers in wearables and healthcare devices	Embedded processors	High-end Processors, AI

European Commission

Industrial Strategy



- Update 2021 EC analysis of strategic dependencies shows challenges in advanced technologies such as microelectronics, cloud and edge computing
 - Recommendation: reinforce processors and semiconductor technology for data processing, communication and related data infrastructure, and new applications of AI
- **Toolbox** to reduce and prevent strategic dependencies:
 - EU Alliance on processors and semiconductor technologies
 - Pursue international partnerships
 - Instruments: IPCEI, RRF, InvestEU, Pact for Skills
- **Digital Compass -** objectives for EU's digital decade (by 2030):
 - 20% of world production of energy-efficient (10x) processors Main R&I instrument: KDT JU, coordination through European alliance
 - 10,000 climate-neutral, highly secure, low-latency edge nodes



EC Member States Declaration on Processors and semiconductor technologies

December 2020, signed so far by **21 Member States** who agreed to:

• Mobilize industrial stakeholders through a future Industrial Alliance



- To establish strategic roadmaps and R&I plans for processor design, deployment and fabrication
- Address common challenges through various funding mechanisms, including where feasible through the national Recovery & Resilience plans
- Design a multi-country project through the development of a proposal for an Important Project of Common European Interest (IPCEI)
- Focus on processors for AI, data processing and communication (5G/6G), edge computing



Overview EC programmes for ECS



- Research and Innovation Horizon Europe
 - Digital, Industry & Space (Cluster 4)
 - Key Digital Technologies, Artificial Intelligence and Robotics, Advanced Computing and Big Data, ...
 - Partnerships
 - Key Digital Technologies JU also Photonics, AI & data, Smart Networks, EuroHPC
- R&I and first industrial deployment
 - IPCEI
- Deployment, capacity and skills
 - Digital Europe Programme, Pact for Skills
- Investment and support programmes
 - NextGenerationEU (RRF), InvestEU, EIC



EC programmes for ECS





A new IPCEI on Microelectronics



European

Objective: strengthen capabilities in digital IC **design** and **manufacturing** for data processing and communication towards **leading-edge** and **low-power** technology

Possible areas of development:

- > Design of **low-power processor** cores and **AI chips** for different vertical markets
- > Design of chips and systems for communication (5G, 6G and other)
- > Development of advanced semiconductor processes (Beyond Moore, More Moore)
- Advanced packaging for 2D/3D heterogeneous integration

<u>Sensing</u>, <u>power</u> electronics, <u>photonics</u> technologies can be integrated if instrumental to the main objectives at system level (eg Edge AloT)

Coordination with KDT JU required – higher TRLs, upto First Industrial Deployment

DEP - Edge AI TEF





- Testing and Experimentation Facilities on Edge AI
- TEF Objectives: European platform bringing together top EU competences to enable companies of any size to test and experiment innovative edge Al components based on advanced low-power computing technologies (e.g. neuromorphic computing)
- TEF will offer end-users: fast-track prototyping, pilot production, industry transfer – support to SMEs via DIHs
- Funding covers mostly CapEx for platform infrastructure
- TEF can be accessed by user companies supported through KDT JU (OpEx) for Edge AI chip development





Horizon Europe Destination: Digital Emerging Technologies

Topics: Electronics, Photonics, Low-power processors, AI, 6G, Robotics, Quantum, Graphene

Sections:

- <u>Ultra-low power processors</u>
- European Innovation Leadership in Electronics
- European Innovation Leadership in Photonics
- 6G and foundational connectivity technologies
- Innovation in AI, Data and Robotics
- Tomorrow's deployable Robots: efficient, robust, safe, adaptive and trusted
- European leadership in Emerging Enabling Technologies (spintronics, 2D- materials, quantum sensing...)
- Flagship on Quantum Technologies: a Paradigm Shift
- Graphene: Europe in the lead

First calls: planned in Q3 2021, Q2 2022





From Cloud to Edge to IoT

- Full protocol stack for IoT integration in edge and cloud platforms
- Next generation (meta) operating systems for Edge Computing Computing continuum





AI, IoT, Edge Computing in KDT JU

Key strategic domain for EU:

- High ambitions aiming for global leadership
- Need ecosystem effort from R&D to pilot lines strenghten EU's IP

To be kept into account:

- Coordination with other ECS-related programmes and instruments: IPCEIs, HE, DEP...
 - Alignment of planning R&I, design and manufacturing
 - Industrial Alliance
- Collaboration across constituencies
 - KDT with: IoT, Cloud, AI-data-robotics, 5G (SNS JU), Photonics



Thank you

Marco Ceccarelli DG CONNECT European Commission



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